

5 Method for the manufacture of through-hole plating on a printed circuit board

Abstract

10 According to the invention, a method for the manufacture of through-hole plating on a printed circuit board is proposed, in which the printed circuit board is first drilled, catalysed and structured. Using an electrochemical depositing process, the through-hole plating is then built up in such a way, that
15 the through-hole plating is suitable for insertion mounting of electronic components. The plating is carried out preferably with nickel or nickel compounds, which require no additional corrosion protection. Through the plating of connection lands with gold or palladium, a direct bonding to the lands is
20 possible.

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